INTEGRATED CIRCUITS

DATA SHEET

74LVC623A Octal transceiver with dual enable (3-State)

Product specification

1998 Jul 29





74LVC623A

FEATURES

- Wide supply voltage range of 1.2V to 3.6V
- In accordance with JEDEC standard no. 8-1A
- Flow-through pin-out architecture
- CMOS low power consumption
- Inputs accept voltages up to 5.5V
- Direct interface with TTL levels
- Output drive capability 50Ω transmission lines @ 85°C

DESCRIPTION

The 74LVC623A is a high performance, low-power, low-voltage Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

The 74LVC623A is an octal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. This octal bus transceiver is designed for asynchronous two-way communication between data buses.

The control function implementation allows maximum flexibility in timing. This device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the levels at the enable inputs (OEAB, OEBA). The enable inputs can be used to disable the device so that the buses are effectively isolated. The dual enable function configuration gives this transceiver the capability to store data by simultaneous enabling of OEAB and OEBA. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of the bus lines are at high impedance OFF-state, both sets of bus lines will remain at their last states. The 8-bit codes appearing on the two sets of buses will be

The '623A' is identical to the '620A' but has true (non-inverting) outputs.

QUICK REFERENCE DATA

GND = 0V: $T_{amb} = 25^{\circ}C$: $t_r = t_r \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay An to Bn; Bn to An	C _L = 50pF V _{CC} = 3.3V	3.3	ns
Cı	Input capacitance		5.0	pF
C _{I/O}	Input/output capacitance		10	pF
C _{PD}	Power dissipation capacitance per latch	Notes 1, 2	32	pF

NOTES:

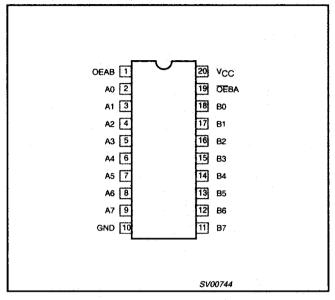
- 1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW) $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where: f_i = input frequency in MHz; C_L = output load capacity in pF; f_o = output frequency in MHz; V_{CC} = supply voltage in V;
- $\Sigma (C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs. 2. The condition is V_I = GND to V_{CC} .

ORDERING AND PACKAGE INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
20-Pin Plastic SO	-40°C to +85°C	74LVC623A D	74LVC623A D	SOT163-1
20-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC623A DB	74LVC623A DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC623A PW	7LVC623APW DH	SOT360-1

74LVC623A

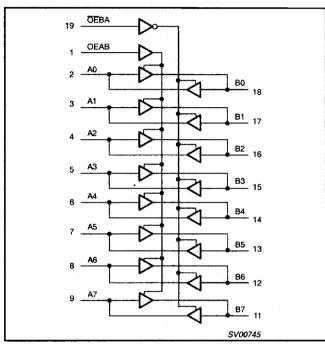
PIN CONFIGURATION



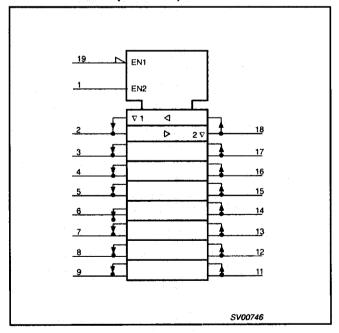
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1 .	OEAB	Direction control
2, 3, 4, 5, 6, 7, 8, 9	A0 – A7	Data inputs/outputs
10	GND	Ground (0V)
18, 17, 16, 15, 14, 13, 12, 11	B0 - B7	Data inputs/outputs
19	ŌĒBA	Output enable input (active LOW)
20	Vcc	Positive supply voltage

LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



74LVC623A

FUNCTION TABLE

INP	UTS	INPUTS/	OUTPUT
OEAB	OEBA	An	Bn
L	Ĺ	A=B	Inputs
Н	н	Inputs	B≔A
L	Н	Z	Z
Н	L	A=B Inputs	Inputs B=A

H = High voltage level

L = Low voltage level

Z =High impedance

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIN	HTS	UNIT
SINIDUL	PANAMETEN	COMPLITIONS	MIN	MAX	UNIT
V _{CC}	DC supply voltage (for max. speed performance)		2.7	3.6	V
Vcc	DC supply voltage (for low-voltage applications)		1.2	3.6	V
Vi	DC input voltage range		0	5.5	V
	DC output voltage range; output HIGH or LOW state		0	Vcc	
Vo	DC output voltage range; output 3-State		0	5.5	\ \ \
T _{amb}	Operating free-air temperature range		-40	+85	°C
t _r , t _f	Input rise and fall times	V _{CC} = 1.2 to 2.7V V _{CC} = 2.7 to 3.6V	0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS¹

In accordance with the Absolute Maximum Rating System (IEC 134)

Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +6.5	٧
lik	DC input diode current	V ₁ < 0	-50	mA
V _I	DC input voltage	Note 2	-0.5 to +6.5	٧
lok	DC output diode current	V _O > V _{CC} or V _O < 0	± 50	mA
	DC output voltage; output HIGH or LOW state	Note 2	-0.5 to V _{CC} +0.5	1/
Vo	DC output voltage; output 3-State	Note 2	-0.5 to 6.5	V
lo	DC output source or sink current	$V_{\rm O} = 0$ to $V_{\rm CC}$	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		± 100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

NOTES:

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2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
absolute-maximum-rated conditions for extended periods may affect device reliability.

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

			ı	IMITS		
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -	40°C to	+85°C	UNIT
			MIN	TYP ¹	MAX	1
V	HICH level lengt veltage	V _{CC} = 1.2V	V _{CC}			.,
V _{IH}	HIGH level Input voltage	V _{CC} = 2.7 to 3.6V	2.0			V
V	LOW/ lovet input veltage	V _{CC} = 1.2V			GND	V
V _{IL}	LOW level input voltage	V _{CC} = 2.7 to 3.6V			0.8	1 °
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -12mA$	V _{CC} - 0.5			
.,	MCU laval autorit valta aa	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -100\mu\text{A}$	V _{CC} -0.2	V _{CC}		
V _{ОН}	HIGH level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -18\text{mA}$	V _{CC} -0.6			\ \
		$V_{CC} = 3.0V$; $V_{I} = V_{IH}$ or V_{IL} ; $I_{O} = -24mA$	V _{CC} -0.8			1
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 12mA$			0.40	
VOL	LOW level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 100\mu A$		GND	0.20	1 v
		$V_{CC} = 3.0V$; $V_1 = V_{IH}$ or V_{IL} ; $I_0 = 24mA$			0.55	
1,	Input leakage current	V _{CC} = 3.6V; V ₁ = 5.5V or GND		±0.1	±5	μА
loz	3-State output OFF-state current	$V_{CC} = 3.6V$; $V_I = V_{IH}$ or V_{IL} ; $V_O = 5.5V$ or GND		0.1	±5	μА
l _{off}	Power off leakage supply	$V_{CC} = 0.0V$; V_{I} or $V_{O} = 5.5V$		0.1	±10	μА
lcc	Quiescent supply current	$V_{CC} = 3.6V$; $V_1 = V_{CC}$ or GND; $I_0 = 0$		0.1	10	μА
Δl _{CC}	Additional quiescent supply current per input pin	$V_{CC} = 2.7V$ to 3.6V; $V_1 = V_{CC} - 0.6V$; $I_0 = 0$		5	500	μА

NOTES

AC CHARACTERISTICS

GND = 0 V; t_r = $t_f\,\leq\,2.5$ ns; C_L = 50 pF

					LIMITS			
SYMBOL	PARAMETER	WAVEFORM	Vc	c = 3.3V ±0).3V	V _{CC}	= 2.7V	UNIT
			MIN	TYP1	MAX	MIN	MAX	
t _{PHL} /t _{PLH}	Propagation delay An to Bn, Bn to An	Figures 1, 4	1.5	2.3	6	1.5	7	ns
t _{PZH} /t _{PZL}	3-State output enable time OEAB to Bn	Figures 3, 4	1.5	4.6	7.6	1.5	8.6	ns
t _{PHZ} /t _{PLZ}	3-State output disable time OEAB to Bn	Figures 3, 4	1.5	4.0	6.5	1.5	7.5	ns
t _{PZH} /t _{PZL}	3-State output enable time OEBA to An	Figures 2, 4	1.5	4.4	7.9	1.5	8.9	ns
t _{PHZ} /t _{PLZ}	3-State output disable time OEBA to An	Figures 2, 4	1.5	3.7	6.5	1.5	7.5	ns

NOTE

^{1.} All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

^{1.} These typical values are at $V_{CC} = 3.3V$ and $T_{amb} = 25$ °C.

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AC WAVEFORMS

 $V_M = 1.5V$ at $V_{CC} \ge 2.7V$ $V_M = 0.5V * V_{CC}$ at $V_{CC} < 2.7V$

 $V_{\mbox{\scriptsize OL}}$ and $V_{\mbox{\scriptsize OH}}$ are the typical output voltage drop that occur with the output load.

 $V_X = V_{OL}$ at $0.3V \ge 2.7V$

 $V_X = V_{OL} + 0.1V_{CC}$ at $V_{CC} < 2.7V$

 $V_Y = V_{OH} - 0.3V$ at $V_{CC} \ge 2.7V$

 $V_Y = V_{OH} - 0.1 V_{CC}$ at $V_{CC} < 2.7 V$

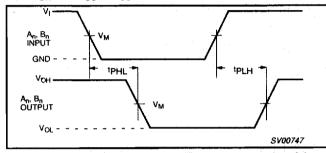


Figure 1. Input (An, Bn) to output (Bn, An) propagation delays.

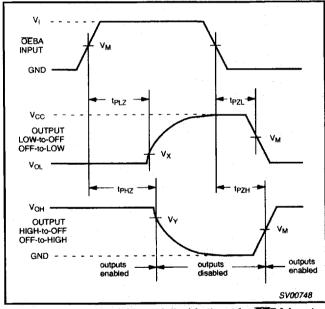


Figure 2. 3-State enable and disable times for OEBA input

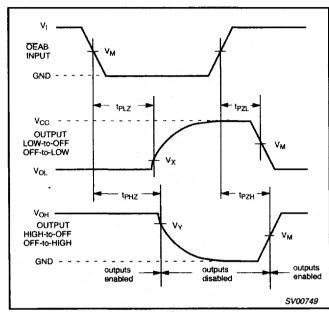


Figure 3. 3-State enable and disable times for OEAB input

TEST CIRCUIT

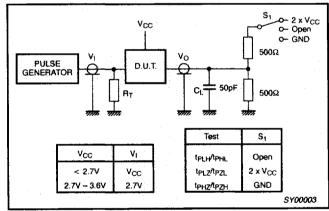
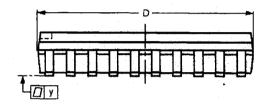


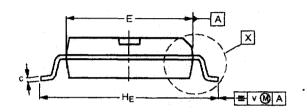
Figure 4. Load circuitry for switching times

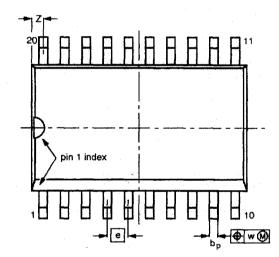
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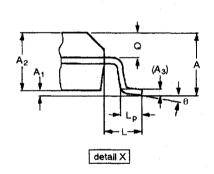
SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1











DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A1	A ₂	A ₃	bp	С	D(1)	E ⁽¹⁾	e	HE	L	Lp	ď	٧	w	у	z ⁽¹⁾	ө
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055		0.043 0.039	0.01	0.01	0.004	0.035 0.016	00

Note

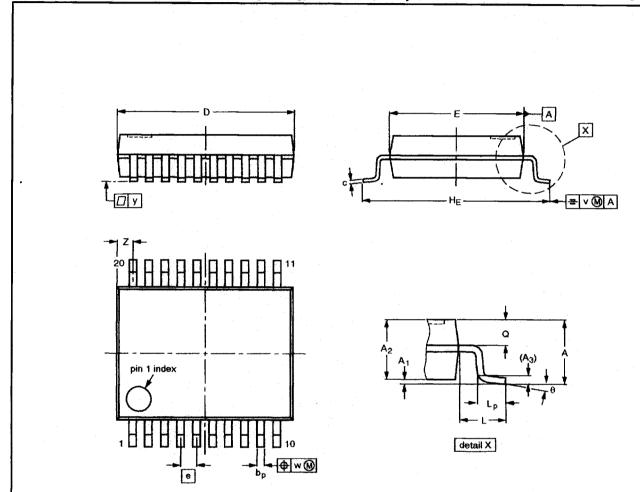
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

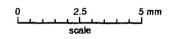
OUTLINE		REFERE	INCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT163-1	075E04	MS-013AC			92-11-17 95-01-24

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SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	А3	рb	c	D ⁽¹⁾	E ⁽¹⁾	٠	HE	L	Ļр	Q	ν	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Mata

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

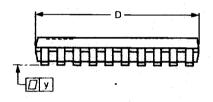
OUTLINE		EUROPEAN	MOULE DATE			
VERSION	VERSION IEC JEDEC EIAJ				PROJECTION	ISSUE DATE
SOT339-1		MO-150AE				93 09 08 95-02-04

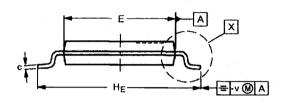
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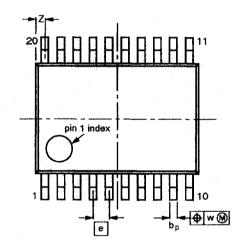
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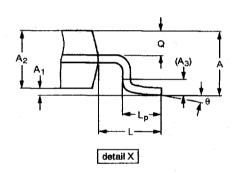
TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

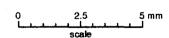
SOT360-1











DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Αı	A ₂	A ₃	bp	С	D ⁽¹⁾	E (2)	e	HE	L	Lp	ø	٧	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1350E DATE	
SOT360-1		MO-153AC				93-96-16 95-02-04	

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74LVC623A

Data sheet status

Data sheet status	Product status	Definition [1] This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.				
Objective specification	Development					
Preliminary specification Qualification		This data sheet contains preliminary data, and supplementary data will be published at a later date Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.				
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.				

^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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